

# EEPROM Serial 2/4/8/16-Kb I<sup>2</sup>C - Automotive Grade 1

## CAV24C02, CAV24C04, CAV24C08, CAV24C16

### Description

The CAV24C02/04/08/16 are a EEPROM Serial 2/4/8/16-Kb I<sup>2</sup>C devices organized internally as 16/32/64 and 128 pages respectively of 16 bytes each. All devices support both the Standard (100 kHz) as well as Fast (400 kHz) I<sup>2</sup>C protocol.

Data is written by providing a starting address, then loading 1 to 16 contiguous bytes into a Page Write Buffer, and then writing all data to non-volatile memory in one internal write cycle. Data is read by providing a starting address and then shifting out data serially while automatically incrementing the internal address count.

External address pins make it possible to address up to eight CAV24C02, four CAV24C04, two CAV24C08 and one CAV24C16 device on the same bus.

### Features

- Automotive AEC-Q100 Grade 1 (-40°C to +125°C) Qualified
- Supports Standard and Fast I<sup>2</sup>C Protocol
- 2.5 V to 5.5 V Supply Voltage Range
- 16-Byte Page Write Buffer
- Hardware Write Protection for Entire Memory
- CAV Prefix for Automotive and Other Applications Requiring Site and Change Control
- Schmitt Triggers and Noise Suppression Filters on I<sup>2</sup>C Bus Inputs (SCL and SDA)
- Low power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

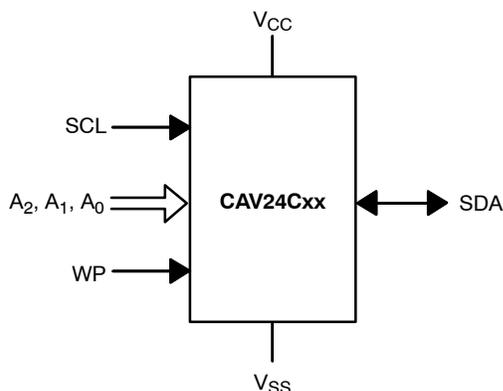


Figure 1. Functional Symbol



TSSOP-8  
Y SUFFIX  
CASE 948AL

WLCSP-4\*\*\*  
C4A SUFFIX  
CASE 567DC

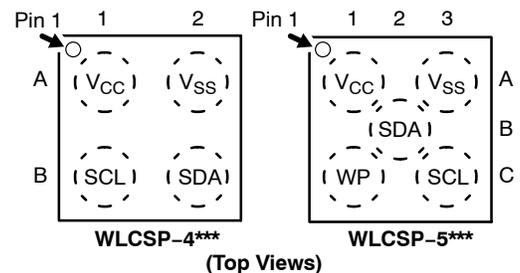
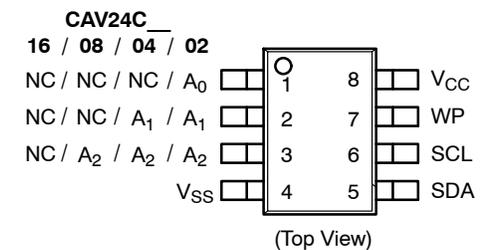


SOIC-8  
W SUFFIX  
CASE 751BD

WLCSP-5\*\*\*  
C5A SUFFIX  
CASE 567DD

### PIN CONFIGURATIONS

SOIC (W), TSSOP (Y)



### PIN FUNCTION

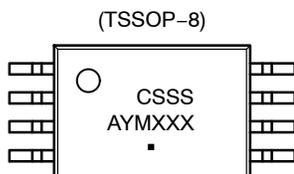
Pin Name	Function
A0, A1, A2	Device Address Input
SDA	Serial Data Input/Output
SCL	Serial Clock Input
WP	Write Protect Input
V <sub>CC</sub>	Power Supply
V <sub>SS</sub>	Ground
NC	No Connect

### ORDERING INFORMATION

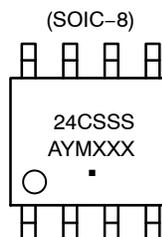
See detailed ordering and shipping information on page 10 of this data sheet.

# CAV24C02, CAV24C04, CAV24C08, CAV24C16

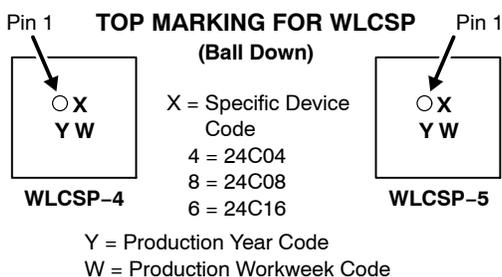
## DEVICE MARKINGS



CSSS = Specific Device Code, where  
 SSS = 02H for CAV24C02  
 SSS = 04K for CAV24C04  
 SSS = 08K for CAV24C08  
 SSS = 16K for CAV24C16  
 A = Assembly Location  
 Y = Production Year (Last Digit)  
 M = Production Month (1-9, O, N, D)  
 XXX = Last Three Digits of Assembly Lot Number  
 ■ = Pb-Free Package



24CSSS = Specific Device Code, where  
 SSS = 02H for CAV24C02  
 SSS = 04K for CAV24C04  
 SSS = 08K for CAV24C08  
 SSS = 16K for CAV24C16  
 A = Assembly Location  
 Y = Production Year (Last Digit)  
 M = Production Month (1-9, O, N, D)  
 XXX = Last Three Digits of Assembly Lot Number  
 ■ = Pb-Free Package



**Table 1. ABSOLUTE MAXIMUM RATINGS**

Parameters	Ratings	Units
Storage Temperature	-65 to +150	°C
Voltage on any pin with respect to Ground (Note 1)	-0.5 to +6.5	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- During input transitions, voltage undershoot on any pin should not exceed -1 V for more than 20 ns. Voltage overshoot on pins A<sub>0</sub>, A<sub>1</sub>, A<sub>2</sub> and WP should not exceed V<sub>CC</sub> + 1 V for more than 20 ns, while voltage on the I<sup>2</sup>C bus pins, SCL and SDA, should not exceed the absolute maximum ratings, irrespective of V<sub>CC</sub>.

**Table 2. RELIABILITY CHARACTERISTICS (Note 2)**

Symbol	Parameter	Min	Units
N <sub>END</sub> (Note 3)	Endurance	1,000,000	Program / Erase Cycles
T <sub>DR</sub>	Data Retention	100	Years

- These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.
- Page Mode, V<sub>CC</sub> = 5 V, 25°C.

## CAV24C02, CAV24C04, CAV24C08, CAV24C16

**Table 3. D.C. OPERATING CHARACTERISTICS**

( $V_{CC} = 2.5\text{ V to }5.5\text{ V}$ ,  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Test Conditions		Min	Max	Units
$I_{CCR}$	Read Current	Read, $f_{SCL} = 400\text{ kHz}$			1	mA
$I_{CCW}$	Write Current	Write, $f_{SCL} = 400\text{ kHz}$			2	mA
$I_{SB}$	Standby Current	All I/O Pins at GND or $V_{CC}$	$T_A = -40^\circ\text{C to }+125^\circ\text{C}$		5	$\mu\text{A}$
$I_L$	I/O Pin Leakage	Pin at GND or $V_{CC}$			2	$\mu\text{A}$
$V_{IL}$	Input Low Voltage			-0.5	$0.3 \times V_{CC}$	V
$V_{IH}$	Input High Voltage	$A_0, A_1, A_2$ and WP		$0.7 \times V_{CC}$	$V_{CC} + 0.5$	V
		SCL and SDA		$0.7 \times V_{CC}$	5.5	V
$V_{OL}$	Output Low Voltage	$V_{CC} > 2.5\text{ V}$ , $I_{OL} = 3\text{ mA}$			0.4	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

**Table 4. PIN IMPEDANCE CHARACTERISTICS** ( $V_{CC} = 2.5\text{ V to }5.5\text{ V}$ ,  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Conditions	Max	Units
$C_{IN}$ (Note 4)	SDA Pin Capacitance	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$ , $V_{CC} = 5.0\text{ V}$	8	pF
	Other Pins		6	pF
$I_{WP}$ (Note 5)	WP Input Current	$V_{IN} < V_{IH}$ , $V_{CC} = 5.5\text{ V}$	130	$\mu\text{A}$
		$V_{IN} < V_{IH}$ , $V_{CC} = 3.6\text{ V}$	120	
		$V_{IN} < V_{IH}$ , $V_{CC} = 2.5\text{ V}$	80	
		$V_{IN} > V_{IH}$	2	
$I_A$ (Note 5)	Address Input Current ( $A_0, A_1, A_2$ )	$V_{IN} < V_{IH}$ , $V_{CC} = 5.5\text{ V}$	50	$\mu\text{A}$
		$V_{IN} < V_{IH}$ , $V_{CC} = 3.6\text{ V}$	35	
		$V_{IN} < V_{IH}$ , $V_{CC} = 2.5\text{ V}$	25	
		$V_{IN} > V_{IH}$	2	

4. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

5. When not driven, the WP, A0, A1 and A2 pins are pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer ( $\sim 0.5 \times V_{CC}$ ), the strong pull-down reverts to a weak current source.

## CAV24C02, CAV24C04, CAV24C08, CAV24C16

**Table 5. A.C. CHARACTERISTICS** (Note 6) ( $V_{CC} = 2.5\text{ V to }5.5\text{ V}$ ,  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Standard		Fast		Units
		Min	Max	Min	Max	
$F_{SCL}$	Clock Frequency		100		400	kHz
$t_{HD:STA}$	START Condition Hold Time	4		0.6		$\mu\text{s}$
$t_{LOW}$	Low Period of SCL Clock	4.7		1.3		$\mu\text{s}$
$t_{HIGH}$	High Period of SCL Clock	4		0.6		$\mu\text{s}$
$t_{SU:STA}$	START Condition Setup Time	4.7		0.6		$\mu\text{s}$
$t_{HD:DAT}$	Data In Hold Time	0		0		$\mu\text{s}$
$t_{SU:DAT}$	Data In Setup Time	250		100		ns
$t_R$	SDA and SCL Rise Time		1000		300	ns
$t_F$ (Note 6)	SDA and SCL Fall Time		300		300	ns
$t_{SU:STO}$	STOP Condition Setup Time	4		0.6		$\mu\text{s}$
$t_{BUF}$	Bus Free Time Between STOP and START	4.7		1.3		$\mu\text{s}$
$t_{AA}$	SCL Low to Data Out Valid		3.5		0.9	$\mu\text{s}$
$t_{DH}$	Data Out Hold Time	100		100		ns
$T_i$ (Note 6)	Noise Pulse Filtered at SCL and SDA Inputs		100		100	ns
$t_{SU:WP}$	WP Setup Time	0		0		$\mu\text{s}$
$t_{HD:WP}$	WP Hold Time	2.5		2.5		$\mu\text{s}$
$t_{WR}$	Write Cycle Time		5		5	ms
$t_{PU}$ (Notes 7, 8)	Power-up to Ready Mode		0.1		0.1	ms

6. Test conditions according to "AC Test Conditions" table.

7. Tested initially and after a design or process change that affects this parameter.

8.  $t_{PU}$  is the delay between the time  $V_{CC}$  is stable and the device is ready to accept commands.

**Table 6. A.C. TEST CONDITIONS**

Input Drive Levels	$0.2 \times V_{CC}$ to $0.8 \times V_{CC}$
Input Rise and Fall Time	$\leq 50\text{ ns}$
Input Reference Levels	$0.3 \times V_{CC}$ , $0.7 \times V_{CC}$
Output Reference Level	$0.5 \times V_{CC}$
Output Test Load	Current Source $I_{OL} = 3\text{ mA}$ ; $C_L = 100\text{ pF}$

### POWER-ON RESET (POR)

Each CAV24Cxx\* incorporates Power-On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

A CAV24Cxx device will power up into Standby mode after  $V_{CC}$  exceeds the POR trigger level and will power down into Reset mode when  $V_{CC}$  drops below the POR trigger level. This bi-directional POR feature protects the device against 'brown-out' failure following a temporary loss of power.

*\*For common features, the CAV24C02/04/08/16 will be referred to as CAV24Cxx.*

### PIN DESCRIPTION

**SCL:** The Serial Clock input pin accepts the Serial Clock generated by the Master.

**SDA:** The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

**A0, A1 and A2:** The Address inputs set the device address when cascading multiple devices. When not driven, these pins are pulled LOW internally.

**WP:** The Write Protect input pin inhibits all write operations, when pulled HIGH. When not driven, this pin is pulled LOW internally.

### FUNCTIONAL DESCRIPTION

The CAV24Cxx supports the Inter-Integrated Circuit ( $I^2C$ ) Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAV24Cxx acts as a Slave device. Master and Slave alternate as either transmitter or receiver.

#### $I^2C$ Bus Protocol

The  $I^2C$  bus consists of two 'wires', SCL and SDA. The two wires are connected to the  $V_{CC}$  supply via pull-up resistors. Master and Slave devices connect to the 2-wire

bus via their respective SCL and SDA pins. The transmitting device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see AC Characteristics).

During data transfer, the SDA line must remain stable while the SCL line is high. An SDA transition while SCL is high will be interpreted as a START or STOP condition (Figure 2). The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake-up' call to all receivers. Absent a START, a Slave will not respond to commands. The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH.

#### Device Addressing

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8-bit serial Slave address. For normal Read/Write operations, the first 4 bits of the Slave address are fixed at 1010 (Ah). The next 3 bits are used as programmable address bits when cascading multiple devices and/or as internal address bits. The last bit of the slave address, R/W, specifies whether a Read (1) or Write (0) operation is to be performed. The 3 address space extension bits are assigned as illustrated in Figure 3.  $A_2$ ,  $A_1$  and  $A_0$  must match the state of the external address pins, and  $a_{10}$ ,  $a_9$  and  $a_8$  are internal address bits.

#### Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9th clock cycle (Figure 4). The Slave will also acknowledge the address byte and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9th clock cycle. As long as the Master acknowledges the data, the Slave will continue transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by issuing a STOP condition. Bus timing is illustrated in Figure 5.

CAV24C02, CAV24C04, CAV24C08, CAV24C16

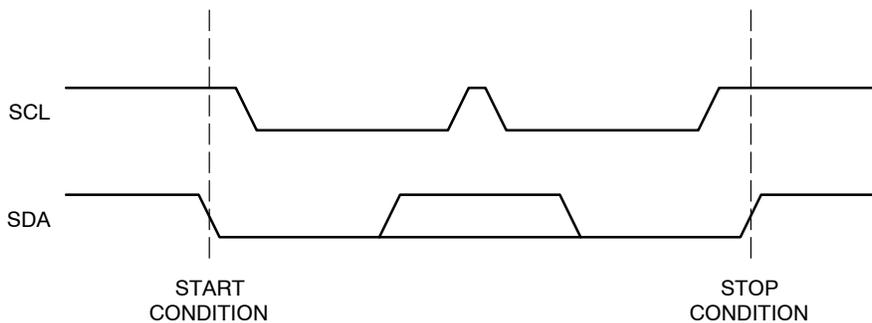


Figure 2. Start/Stop Timing

1	0	1	0	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	R/W	CAV24C02
1	0	1	0	A <sub>2</sub>	A <sub>1</sub>	a <sub>8</sub>	R/W	CAV24C04
1	0	1	0	A <sub>2</sub>	a <sub>9</sub>	a <sub>8</sub>	R/W	CAV24C08
1	0	1	0	a <sub>10</sub>	a <sub>9</sub>	a <sub>8</sub>	R/W	CAV24C16

Figure 3. Slave Address Bits

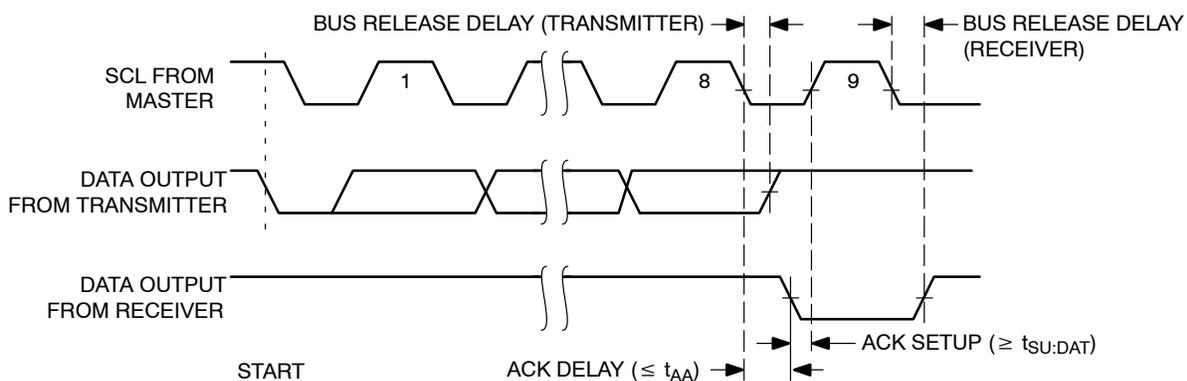


Figure 4. Acknowledge Timing

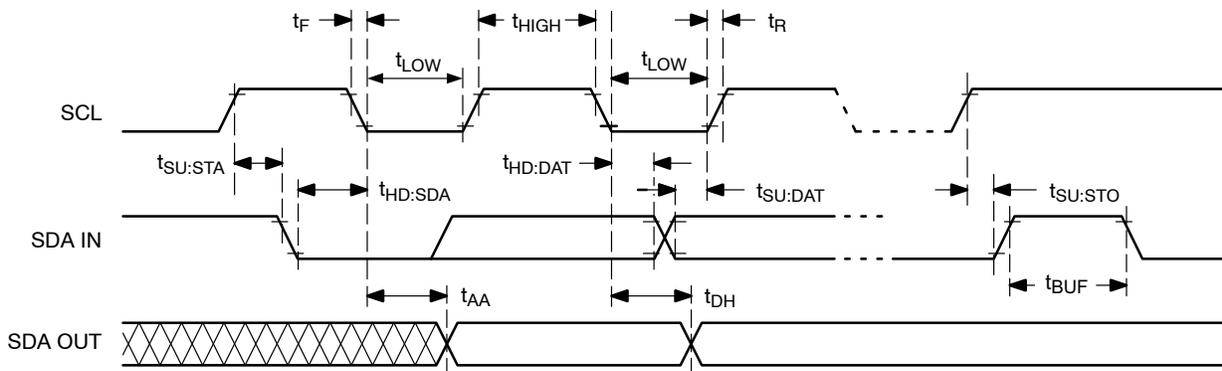


Figure 5. Bus Timing

WRITE OPERATIONS

**Byte Write**

In Byte Write mode, the Master sends the START condition and the Slave address with the R/W bit set to zero to the Slave. After the Slave generates an acknowledge, the Master sends the byte address that is to be written into the address pointer of the CAV24Cxx. After receiving another acknowledge from the Slave, the Master transmits the data byte to be written into the addressed memory location. The CAV24Cxx device will acknowledge the data byte and the Master generates the STOP condition, at which time the device begins its internal Write cycle to nonvolatile memory (Figure 6). While this internal cycle is in progress ( $t_{WR}$ ), the SDA output will be tri-stated and the CAV24Cxx will not respond to any request from the Master device (Figure 7).

**Page Write**

The CAV24Cxx writes up to 16 bytes of data in a single write cycle, using the Page Write operation (Figure 8). The Page Write operation is initiated in the same manner as the Byte Write operation, however instead of terminating after the data byte is transmitted, the Master is allowed to send up to fifteen additional bytes. After each byte has been transmitted the CAV24Cxx will respond with an acknowledge and internally increments the four low order address bits. The high order bits that define the page address remain unchanged. If the Master transmits more than sixteen bytes prior to sending the STOP condition, the address counter ‘wraps around’ to the beginning of page and previously transmitted data will be overwritten. Once all

sixteen bytes are received and the STOP condition has been sent by the Master, the internal Write cycle begins. At this point all received data is written to the CAV24Cxx in a single write cycle.

**Acknowledge Polling**

The acknowledge (ACK) polling routine can be used to take advantage of the typical write cycle time. Once the stop condition is issued to indicate the end of the host’s write operation, the CAV24Cxx initiates the internal write cycle. The ACK polling can be initiated immediately. This involves issuing the start condition followed by the slave address for a write operation. If the CAV24Cxx is still busy with the write operation, NoACK will be returned. If the CAV24Cxx has completed the internal write operation, an ACK will be returned and the host can then proceed with the next read or write operation.

**Hardware Write Protection**

With the WP pin held HIGH, the entire memory is protected against Write operations. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAV24Cxx. The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAV24Cxx will not acknowledge the data byte and the Write request will be rejected.

**Delivery State**

The CAV24Cxx is shipped erased, i.e., all bytes are FFh.

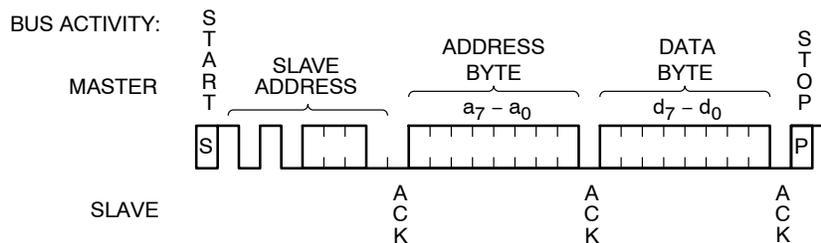


Figure 6. Byte Write Sequence

CAV24C02, CAV24C04, CAV24C08, CAV24C16

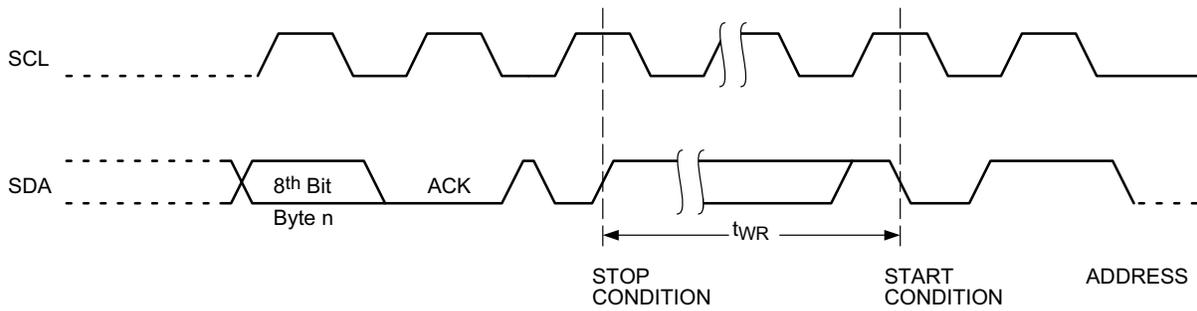


Figure 7. Write Cycle Timing

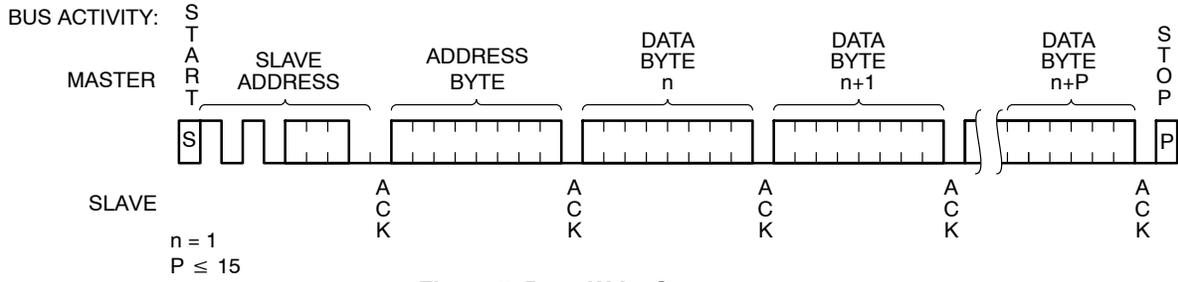


Figure 8. Page Write Sequence

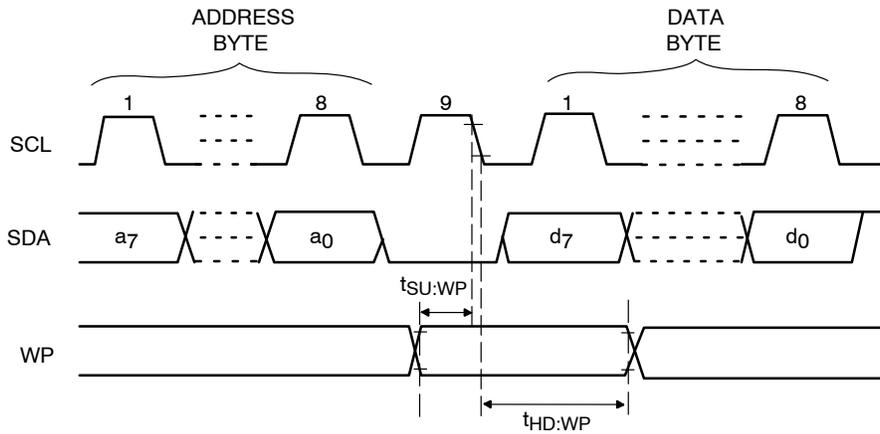


Figure 9. WP Timing

READ OPERATIONS

Immediate Read

Upon receiving a Slave address with the R/W bit set to '1', the CAV24Cxx will interpret this as a request for data residing at the current byte address in memory. The CAV24Cxx will acknowledge the Slave address, will immediately shift out the data residing at the current address, and will then wait for the Master to respond. If the Master does not acknowledge the data (NoACK) and then follows up with a STOP condition (Figure 10), the CAV24Cxx returns to Standby mode.

Selective Read

Selective Read operations allow the Master device to select at random any memory location for a read operation. The Master device first performs a 'dummy' write operation by sending the START condition, slave address and byte

address of the location it wishes to read. After the CAV24Cxx acknowledges the byte address, the Master device resends the START condition and the slave address, this time with the R/W bit set to one. The CAV24Cxx then responds with its acknowledge and sends the requested data byte. The Master device does not acknowledge the data (NoACK) but will generate a STOP condition (Figure 11).

Sequential Read

If during a Read session, the Master acknowledges the 1<sup>st</sup> data byte, then the CAV24Cxx will continue transmitting data residing at subsequent locations until the Master responds with a NoACK, followed by a STOP (Figure 12). In contrast to Page Write, during Sequential Read the address count will automatically increment to and then wrap-around at end of memory (rather than end of page).

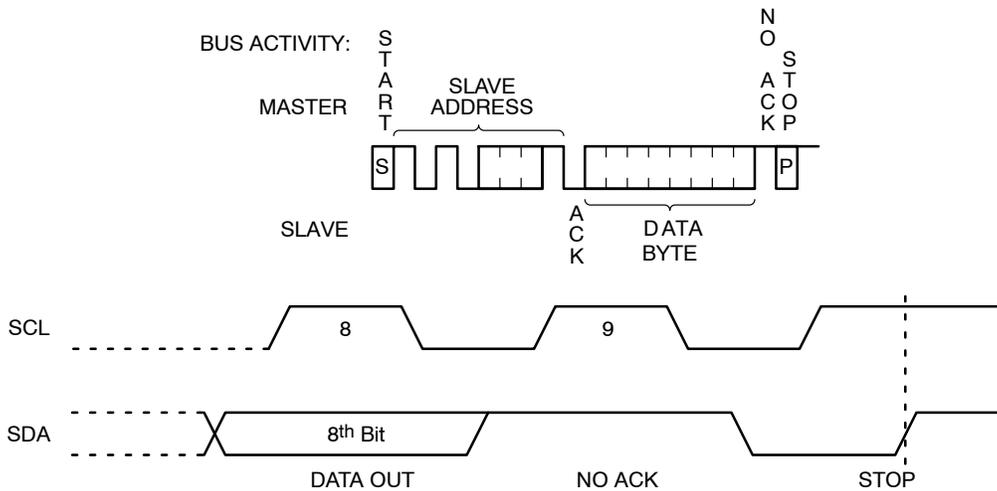


Figure 10. Immediate Read Sequence and Timing

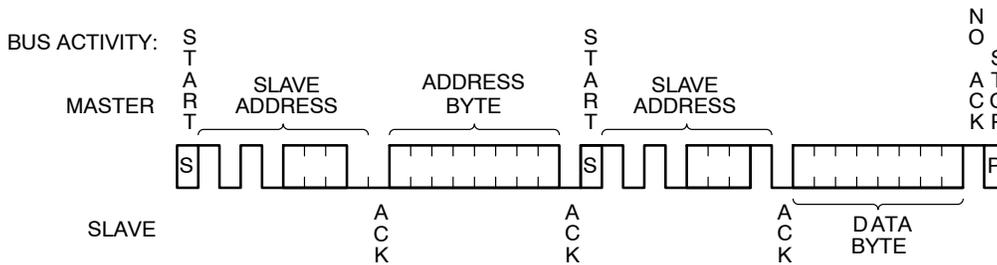


Figure 11. Selective Read Sequence

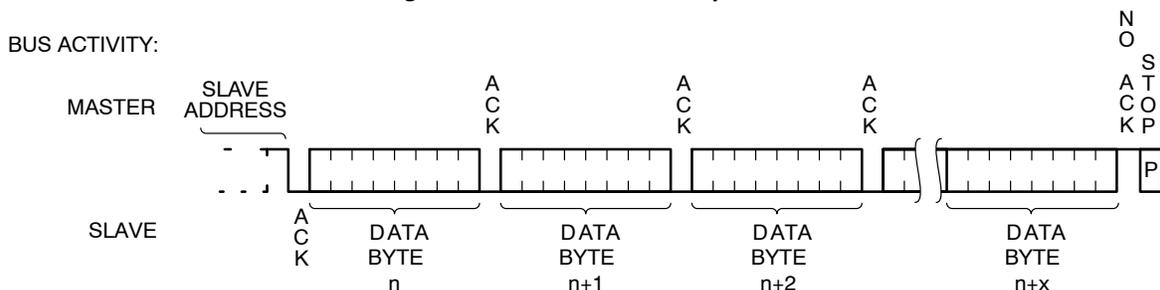


Figure 12. Sequential Read Sequence

## CAV24C02, CAV24C04, CAV24C08, CAV24C16

### CAV24C02 ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping <sup>†</sup>
CAV24C02WE-GT3	24C02H	SOIC-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C02YE-GT3	C02H	TSSOP-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel

### CAV24C04 ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping <sup>†</sup>
CAV24C04WE-GT3	24C04K	SOIC-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C04YE-GT3	C04K	TSSOP-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C04C4ATR	4	WLCSP-4	-40°C to +125°C	N/A	5,000 Units / Tape & Reel
CAV24C04C5ATR	4	WLCSP-5	-40°C to +125°C	N/A	5,000 Units / Tape & Reel

### CAV24C08 ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping <sup>†</sup>
CAV24C08WE-GT3	24C08K	SOIC-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C08YE-GT3	C08K	TSSOP-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C08C4ATR	8	WLCSP-4	-40°C to +125°C	N/A	5,000 Units / Tape & Reel
CAV24C08C4CTR*	8	WLCSP-4	-40°C to +125°C	N/A	5,000 Units / Tape & Reel
CAV24C08C5ATR	8	WLCSP-5	-40°C to +125°C	N/A	5,000 Units / Tape & Reel

\*CAV24C08C4CTR is a backside coated version. Contact factory for other densities.

### CAV24C16 ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping <sup>†</sup>
CAV24C16WE-GT3	24C16K	SOIC-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C16YE-GT3	C16K	TSSOP-8	-40°C to +125°C	NiPdAu	3,000 Units / Tape & Reel
CAV24C16C4ATR	6	WLCSP-4	-40°C to +125°C	N/A	5,000 Units / Tape & Reel
CAV24C16C5ATR	6	WLCSP-5	-40°C to +125°C	N/A	5,000 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

9. All packages are RoHS-compliant (Lead-free, Halogen-free).

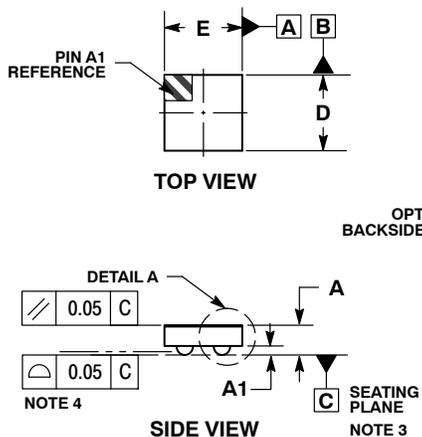
onsemi is licensed by the Philips Corporation to carry the I<sup>2</sup>C bus protocol.



SCALE 4:1

WLCSP4, 0.84x0.86  
CASE 567DC  
ISSUE F

DATE 14 Jul 2016



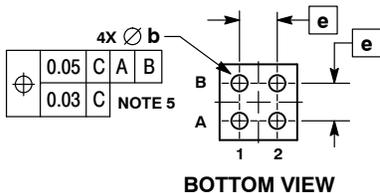
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
  4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
  5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.38
A1	0.08	0.10	0.12
A2	0.23 REF		
A3	0.025 REF		
b	0.16	0.18	0.20
D	0.82	0.84	0.86
E	0.84	0.86	0.88
e	0.40 BSC		

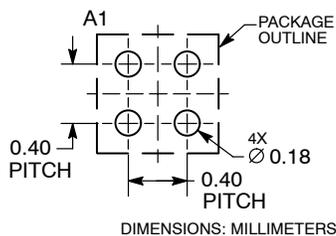
GENERIC  
MARKING DIAGRAM\*



- X = Specific Device Code
- Y = Year
- M = Date Code



RECOMMENDED  
SOLDERING FOOTPRINT\*



\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

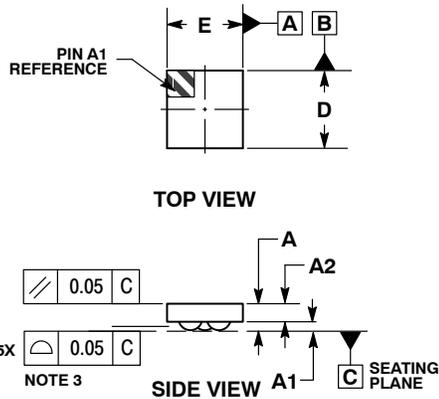
DOCUMENT NUMBER:	98AON56821E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP4, 0.84X0.86	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

SCALE 4:1

WLCSP5, 0.86x0.84  
CASE 567DD  
ISSUE D

DATE 14 JUL 2016



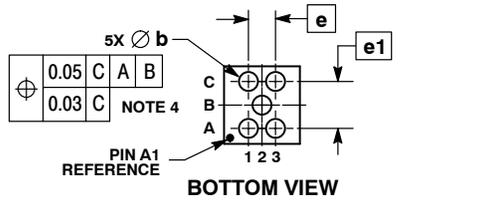
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
  4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
  5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.39
A1	0.10	0.12	0.14
A2	0.23 REF		
b	0.14	0.16	0.18
D	0.84	0.86	0.88
E	0.82	0.84	0.86
e	0.30 BSC		
e1	0.52 BSC		

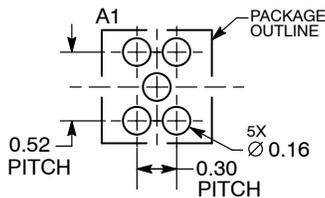
GENERIC MARKING DIAGRAM\*



- X = Specific Device Code
- Y = Year
- M = Date Code



RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

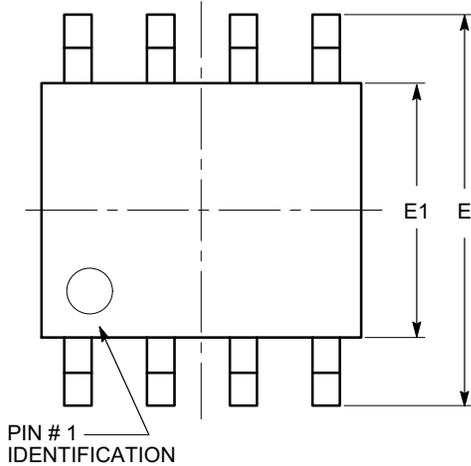
\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

DOCUMENT NUMBER:	98AON56899E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP5, 0.86X0.84	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

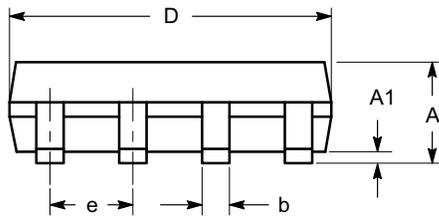
**SOIC-8, 150 mils**  
CASE 751BD  
ISSUE O

DATE 19 DEC 2008

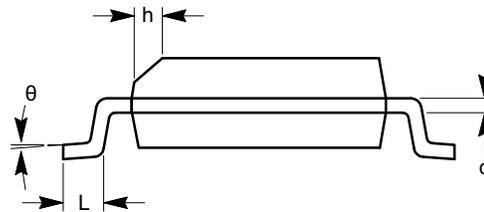


**TOP VIEW**

SYMBOL	MIN	NOM	MAX
A	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
c	0.19		0.25
D	4.80		5.00
E	5.80		6.20
E1	3.80		4.00
e	1.27 BSC		
h	0.25		0.50
L	0.40		1.27
$\theta$	0°		8°



**SIDE VIEW**



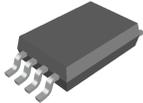
**END VIEW**

**Notes:**

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

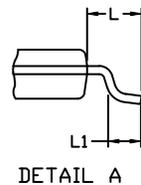
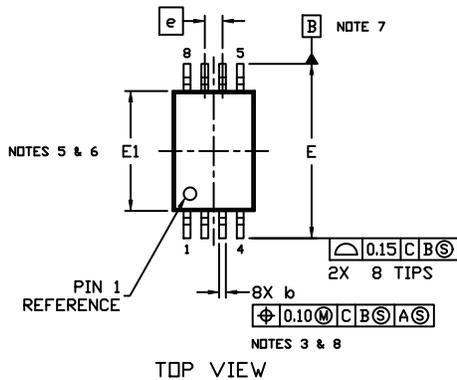
<b>DOCUMENT NUMBER:</b>	<b>98AON34272E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>SOIC-8, 150 MILS</b>	<b>PAGE 1 OF 1</b>

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.



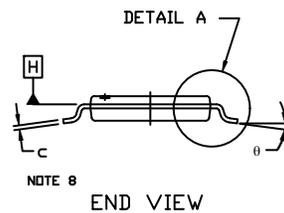
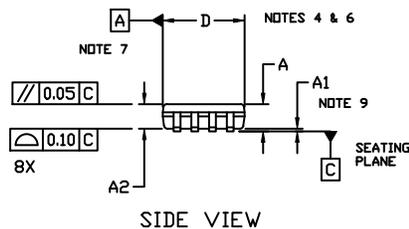
TSSOP8, 4.4x3.0, 0.65P  
CASE 948AL  
ISSUE A

DATE 20 MAY 2022



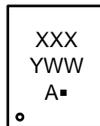
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL NOT BE 0.15 IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM PLANE H.
7. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
8. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
9. A1 IS DEFINED AS THE LOWEST VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



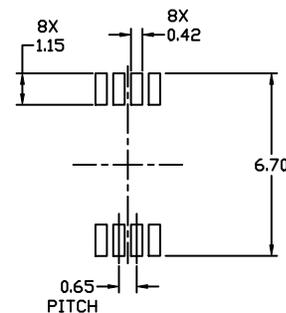
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	1.20
A1	0.05	---	0.15
A2	0.80	0.90	1.05
b	0.19	---	0.30
c	0.09	---	0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.70
θ	0°	---	8°

GENERIC MARKING DIAGRAM\*



- XXX = Specific Device Code
- Y = Year
- WW = Work Week
- A = Assembly Location
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

DOCUMENT NUMBER:	98AON34428E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP8, 4.4X3.0, 0.65P	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at [www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)